EAST Search History

Ref#	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20070121696"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:26
S2	0	@ad<="20041104" and (257/079).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:27
S3	1631	@ad<="20041104" and (257/79).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:27
S4	2379	@ad<="20041104" and (257/99).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:29

S6	2535	@ad<="20041104" and (257/98).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:29
S7	2	"20040012958"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:31
S8	2	("6898340").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/07 09:31
S9	349	@ad<="20041104" and (362/241).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:33
S10	328	@ad<="20041104" and (257/E33.06).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:34

S11	700	@ad<="20041104" and (257/E33.065).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:34
S12	989	@ad<="20041104" and (257/E33.066).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:35
S13	760	@ad<="20041104" and (257/E33.068).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:36
S14	576	@ad<="20041104" and (257/E33.072).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:36
S15	287	@ad<="20041104" and (257/E33.074).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:37

S16	603	@ad<="20041104" and (257/E33.075).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:37
S17	4427	@ad<="20041104" and (385/14).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:50
S18	6	("20030042505" "20030183835" "5900650" "6426512" "6825499").PN. OR ("6898340").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/07 09:52
S19	29	@ad<="20041104" and "light emitting element" and mount\$4 with substrate with silicon with single	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 10:00
S20	12	@ad<="20041104" and "light emitting element" and mount\$4 with substrate with silicon with reflect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 10:01

S21	65	@ad<="20041104" and ("light emitting element" or "light emitting device") and mount\$4 with substrate with silicon with single	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 10:03
S22	88	@ad<="20041104" and single with silicon with mount\$4 and ("light emitting element" or "light emitting device")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 10:04
S23	69	@ad<="20041104" and single with silicon with mount\$4 and ("light emitting element" or "light emitting device") and reflect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 10:04
S24	1077	@ad<="20041104" and single with silicon with substrate and ("light emitting element" or "light emitting device")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 10:12
S25	245	@ad<="20041104" and single with silicon with substrate same ("light emitting element" or "light emitting device")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 10:12

S26	100	@ad<="20041104" and single with silicon with substrate same ("light emitting element" or "light emitting device") and reflect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 10:13
S27	917	@ad<="20041104" and (257/E31.117).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 14:31
S28	540	@ad<="20041104" and (257/E31.127).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 14:31
S29	23	("20010040245" "20020123164" "20030006418" "20040056260" "4918497" "4966862" "5027168" "5210051" "5338944" "5393993" "5416342" "5523589" "5604135" "5631190" "5739554" "5912477" "6084175" "6120600" "6187606" "6201262"	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/07 15:02

		"6214107" "6885033" "6893892").PN. OR ("7202181").URPN.				
S31	848	@ad<="20041104" and (257/98).ccls. and mount \$4 and reflect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 15:13
S32	2	"jp 07007184"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 15:18
S33	471	"WATANABE" and "OMRON"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 15:21
S34	56	"WATANABE" and "OMRON" and "light emitting"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 15:21

S35	171	@ad<="20041104" and submount\$4 with substrate same ("light emitting element" or "light emitting device" or "LED") and reflect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 15:42
S37	53	@ad<="20041104" and "mounting substrate" same ("light emitting element" or "light emitting device" or "LED") with reflect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 05:00
S38	159	@ad<="20041104" and mount\$4 with substrate with silicon same ("light emitting element" or "light emitting device" or "LED") and reflect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 05:07
S39	141	@ad<="20041104" and mount\$4 with substrate with silicon same reflect\$3 and ("light emitting element" or "light emitting device" or "LED")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 05:07

S40	59	emitting element" or "light	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 05:42
S41	87	@ad<="20041104" and "mounting substrate" with reflect\$4 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 05:48
S42	6	("20030042505" "20030183835" "5900650" "6426512" "6825499").PN. OR ("6898340").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/08 05:53
S43	0	"EP 0413489"	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/08 05:56
S44	0	"EP 413489"	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/08 05:56
S45	0	"EP 00413489"	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/08 05:56
S46	17	@ad<="20041104" and submount with single with silicon and ("light emitting element" or "light emitting device" or "LED")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 05:57

S47	191	"Ishii Yorishige" and SHARP	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 05:59
S50	86	@ad<="20041104" and packag\$4 same optical same silicon with substrate and reflector	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 06:07
S56	561	@ad<="20041104" and mount\$4 with substrate and receiv\$3 with ("light emitting element" or "light emitting device" or "LED") with reflect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 06:17
S57	34	@ad<="20041104" and mount\$4 with substrate with silicon and receiv\$3 with ("light emitting element" or "light emitting device" or "LED") with reflect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 06:19

S58	5	("20020163001" "20020163006" "20030189830" "6501103").PN. OR ("6930332").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/08 06:29
S59	9	("20020130326" "20020195935" "20030006469" "20030008431" "20030038295" "5998925" "6069440" "6252254" "6734466"). PN. OR ("6909123"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/08 06:31
S60	545	@ad<="20041104" and (257/98).ccls. and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 06:46
S61	621	@ad<="20041104" and (257/98).ccls. and reflector	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 06:48

S62	77	("20020123164"	US-PGPUB;	OR	ON	2007/09/08
14 14 14 14 14 14 14 14 14		"20030006418"	USPAT; USOCR			06:50
24 24 24 24 24 24 24 24 24 24 24 24 24 2		"20030032212"				
74 74 74 74 74 74 74 74		"20030067264"				
24 24 24 24 24 24 24		"20030080341"				
24 24 24 24 24 24 24 24		"20030098459"				
24 24 24 24 24 24 24 24 24		"20030153861"				
A A A A A A A A A		"20030173575"				
A A A A A A A A A A A A A A A A A A A		"20040041222"				
21 21 21 21 21 21 21 21		"20040041757"				
A A A A A A A A		"20040056260"				
20 20 20 20 20 20 20 20 20 20 20 20 20 2		"20040079957"				
24 24 24 24 24 24 24 24 24 24 24 24 24 2		"20040095738"				
A A A A A A A A A A A A A A A A A A A		"20040211970"				
24 24 24 24 24 24 24		"20040222433"				
A A A A A		"4042552" "4107238"				
A		"4141941" "4562018"				
24 24 24 24 24 24 24 24 24 24		"4650922" "4794048"				
74 74 74 74 74 74 74 74		"4826424" "4918497"				
24 24 24 24 24 24 24 24		"4935665" "4966862"				
21 21 21 21 21 21		"5024966" "5027168"				
21 23 23 24 24 24 24 24 24		"5087949" "5110278"				
A A A A A A A		"5143660" "5210051"				
A A A A A A A A A		"5277840" "5298768"				
24 24 24 24 24 24 24 24 24 24 24 24 24 2		"5338944" "5374668"				
24 24 24 24 24 24 24 24 24 24 24 24 24 2		"5393993" "5416342"				
24 24 24 24 24 24 24 24 24 24 24 24 24 2		"5523589" "5604135"				
		"5631190" "5739554"				
# # # # # # # # # #		"5753730" "5813753"				

		"5959316" "5968422" "6060729" "6066861" "6069440" "6120600" "6156242" "6177688" "6184544" "6187606" "6201262" "6219223" "6252254" "6329676" "6373188" "6383417" "6391231" "6404125" "6480389" "6498355" "6599768" "6562643" "6599768" "6639356" "6686609" "6707069" "6744077" "6783362" "6791151" "6824294"). PN. OR ("7183587"). URPN.				
S63	48	@ad<="20041104" and ("light emitting element" or "light emitting device" or "LED") same reflector with (dielectric or insulat\$4) with metal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 08:36

S64	10	@ad<="20041104" and ("light emitting element" or "light emitting device" or "LED") same reflector with (dielectric or insulat\$4) with "reflective metal"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 08:36
S65	46	@ad<="20041104" and reflector with (dielectric or insulat\$4) with "reflective metal"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 08:45
S66	2	("5169229").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/08 08:49
S67	12	("4322130" "5007710"). PN. OR ("5169229"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/08 08:51
S68	711	@ad<="20041104" and reflect\$4 with (dielectric or insulat\$4) with "reflective metal"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/08 14:05

S69	64	@ad<="20041104" and	US-PGPUB;	OR	ON	2007/09/08
		reflector same (dielectric	USPAT; EPO;))))	14:06
		or insulat\$4) with	JPO;			
		"reflective metal"	DERWENT;			
24 24 24 25 26 26 27 28 28 28 28 28 28 28 28 28 28 28 28 28			IBM_TDB			

9/8/07 5:04:40 PM

C:\Documents and Settings\tle10\My Documents\EAST\Workspaces\Packaging, Flip Chip, BGA, Solder Ball, Bonding Pad, Testing\10579008 packaging submount LED 257.wsp